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To Be Fixed To The Box. • The Box Should Not Be Of A Slick Coating That Will Make The Box Hard To Handle. • All Shoes Must Face One Direction. • All Footwear Shoeboxes Are Required To Be Labeled With A UPC-A, EAN Or Interleaved 2 of 5 Labels. • Stickers Should Be Pla 3th, 2024.

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Length And Overall Diameter (O.D.) Of The Cable Or
Wire To Be Rewound. A Reel Not Matched To The
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